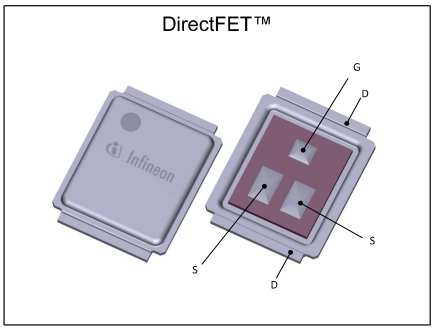
MOSFET

OptiMOS™ 5, 150 V

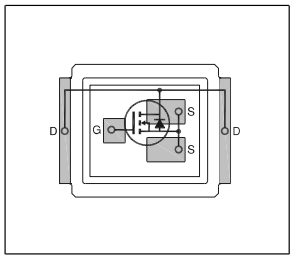


Features

- Lead free, ultra thin double sided cooling package
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low on -resistance $R_{DS(on)}$
- N-channel normal level
- 100% avalanche tested

Applications

- Brushed Motor drive, Synchronous rectifier and BLDC Motor drive applications
- Battery powered circuits
- Half-bridge and full-bridge topologies
- Resonant mode power supplies
- OR-ing and redundant power switches
- DC/DC and AC/DC converters
- DC/AC Inverters



Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	150	V
$R_{DS(on),max}$	11.3	mΩ
I_D	60	A
Q_{oss}	87	nC
Q_G (0V..10V)	33	nC

Type / Ordering Code	Package	Marking	Related Links
IRF150DM115	MG-WDSON-5	M115	-

Table of Contents

1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- - -	- - -	60 38 11	A	V_{GS}=10 V, T_C=25 °C V_{GS}=10 V, T_C=100 °C V_{GS}=10 V, T_A=25 °C, R_{THJA}=45 °C/W[2]
Pulsed drain current[3]	$I_{D,pulse}$	-	-	240	A	T_A=25 °C
Avalanche energy, single pulse[4]	E_{AS}	-	-	72	mJ	I_D=45 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	- -	- -	78 2.8	W	T_C=25 °C T_A=25 °C, R_{THJA}=45 °C/W[2]
Operating and storage temperature	T_j, T_{stg}	-40	-	150	°C	-

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.6	°C/W	-
Thermal resistance, junction - ambient, double sided cooling	R_{thJA}[5]	-	12.5	-	°C/W	-
Thermal resistance, junction - ambient, mounted on minimum foot print	R_{thJA}[6]	-	20	-	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}[2]	-	-	45	°C/W	-
Device on PCB	$R_{thJ-PCB}$	-	0.75	-	°C/W	-
Soldering temperature, wave andreflow soldering are allowed	T_{sold}	-	-	260	°C	reflow MSL3

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.
[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.
[3] See Diagram 3 for more detailed information
[4] See Diagram 13 for more detailed information
[5] Used double sided cooling, mounting pad with large heat sink
[6] Mouted on minimum footprint full size board with metalized back with small clip heat sink

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	150	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	3	3.8	4.6	V	V_{DS}=V_{GS}, I_D=106 µA
Zero gate voltage drain current	I_{DSS}	- -	0.1 10	1 100	µA	V_{DS}=120 V, V_{GS}=0 V, T_j=25 °C V_{DS}=120 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	-	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	8.5	11.3	mΩ	V_{GS}=10 V, I_D=45 A
Gate resistance	R_G	-	0.7	-	Ω	-
Transconductance[1]	g_{fs}	33	66	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=45 A

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance[1]	C_{iss}	-	2300	3000	pF	V_{GS}=0 V, V_{DS}=75 V, f=1 MHz
Output capacitance[1]	C_{oss}	-	580	780	pF	V_{GS}=0 V, V_{DS}=75 V, f=1 MHz
Reverse transfer capacitance[1]	C_{rss}	-	41	70	pF	V_{GS}=0 V, V_{DS}=75 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	11	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=45 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r	-	21	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=45 A, $R_{G,ext}$=1.6 Ω
Turn-off delay time	$t_{d(off)}$	-	14	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=45 A, $R_{G,ext}$=1.6 Ω
Fall time	t_f	-	14	-	ns	V_{DD}=75 V, V_{GS}=10 V, I_D=45 A, $R_{G,ext}$=1.6 Ω

Table 6 Gate charge characteristics[2]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	13.2	-	nC	V_{DD}=75 V, I_D=45 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$	-	8.7	-	nC	V_{DD}=75 V, I_D=45 A, V_{GS}=0 to 10 V
Gate to drain charge[1]	Q_{gd}	-	8.0	12	nC	V_{DD}=75 V, I_D=45 A, V_{GS}=0 to 10 V
Switching charge	Q_{sw}	-	12.5	-	nC	V_{DD}=75 V, I_D=45 A, V_{GS}=0 to 10 V
Gate charge total[1]	Q_g	-	33	50	nC	V_{DD}=75 V, I_D=45 A, V_{GS}=0 to 10 V
Gate plateau voltage	$V_{plateau}$	-	5.7	-	V	V_{DD}=75 V, I_D=45 A, V_{GS}=0 to 10 V
Output charge[1]	Q_{oss}	-	87	115	nC	V_{DS}=75 V, V_{GS}=0 V

[1] Defined by design. Not subject to production test.
[2] See "Gate charge waveforms" for parameter definition

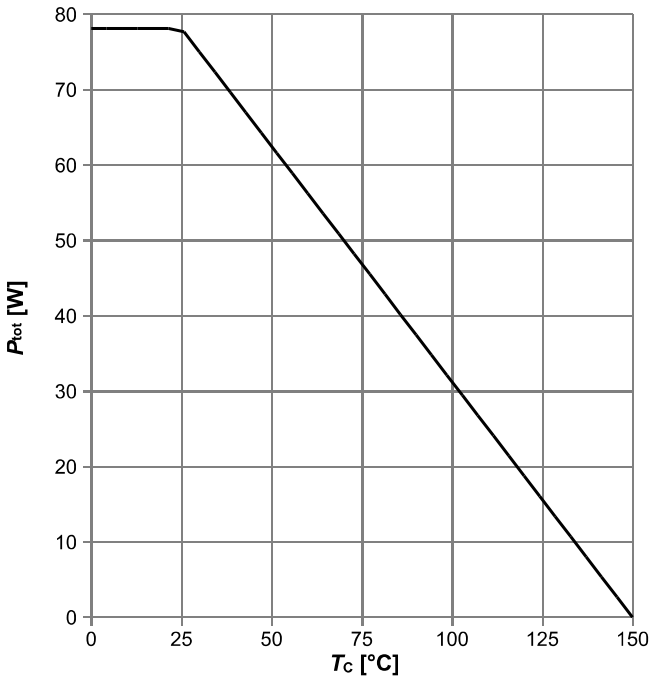
Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	60	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$	-	-	240	A	T_C=25 °C
Diode forward voltage	V_{SD}	-	0.9	1.2	V	V_{GS}=0 V, I_F=45 A, T_j=25 °C
Reverse recovery time[1)]	t_{rr}	-	39	78	ns	V_R=75 V, I_F=45 A, di_F/dt=100 A/µs
Reverse recovery charge[1)]	Q_{rr}	-	47	94	nC	V_R=75 V, I_F=45 A, di_F/dt=100 A/µs

[1)] Defined by design. Not subject to production test.

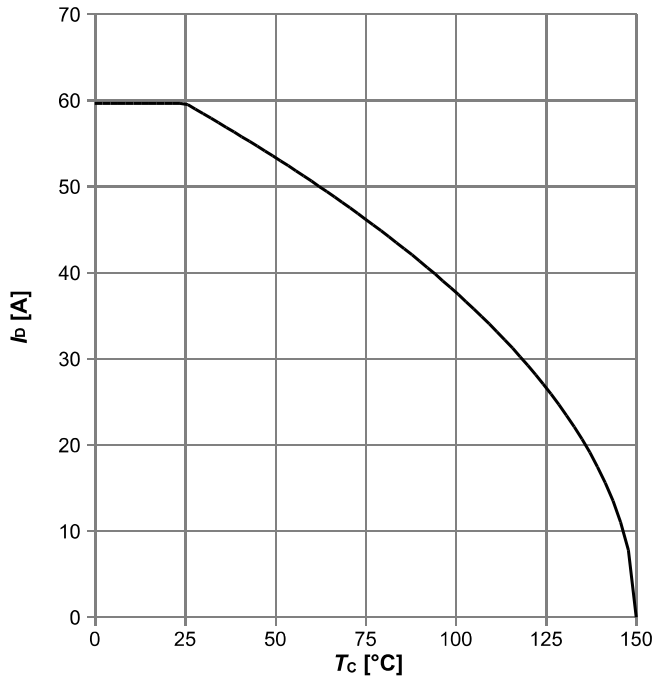
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



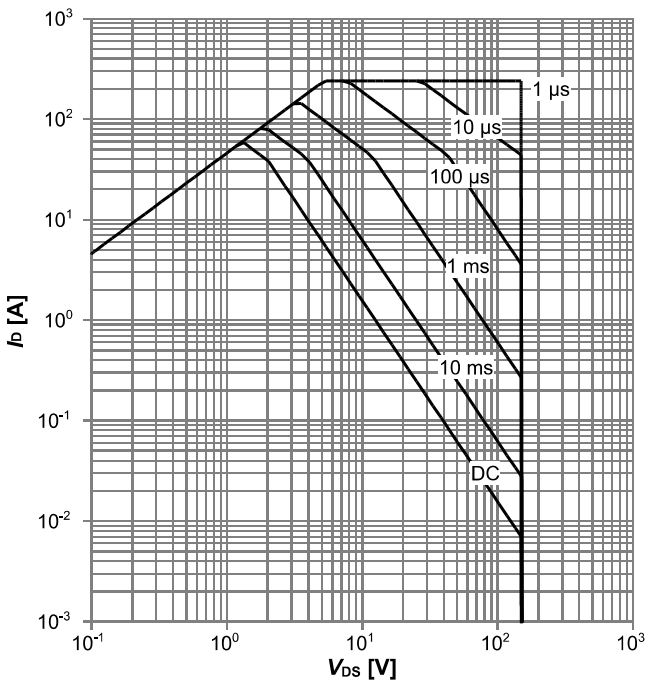
P_{tot}=f(T_C)

Diagram 2: Drain current



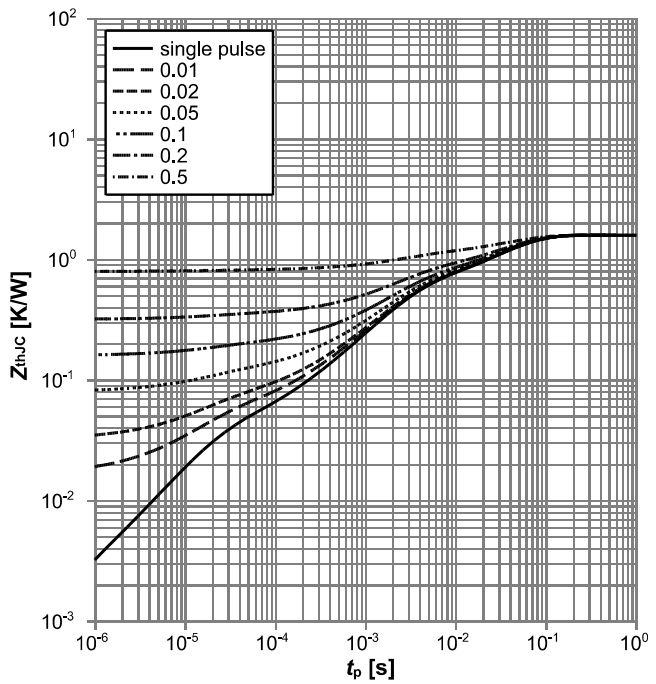
I_D=f(T_C); V_{GS}≥10 V

Diagram 3: Safe operating area



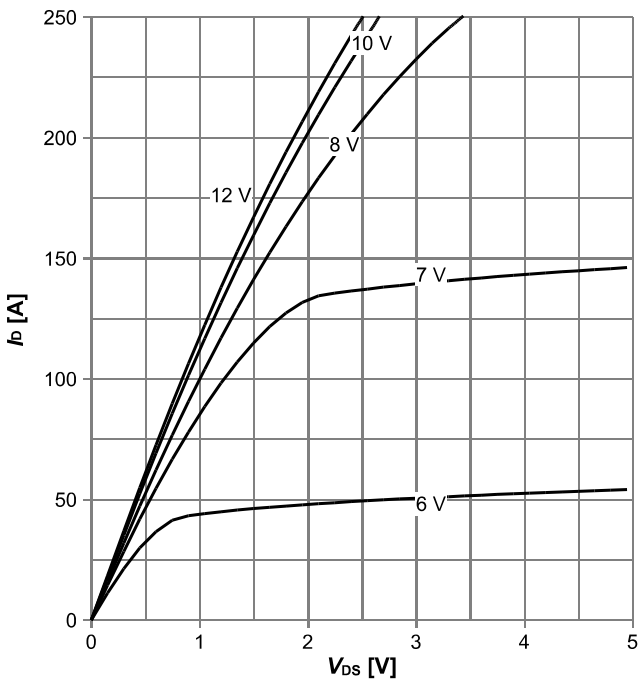
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 4: Max. transient thermal impedance



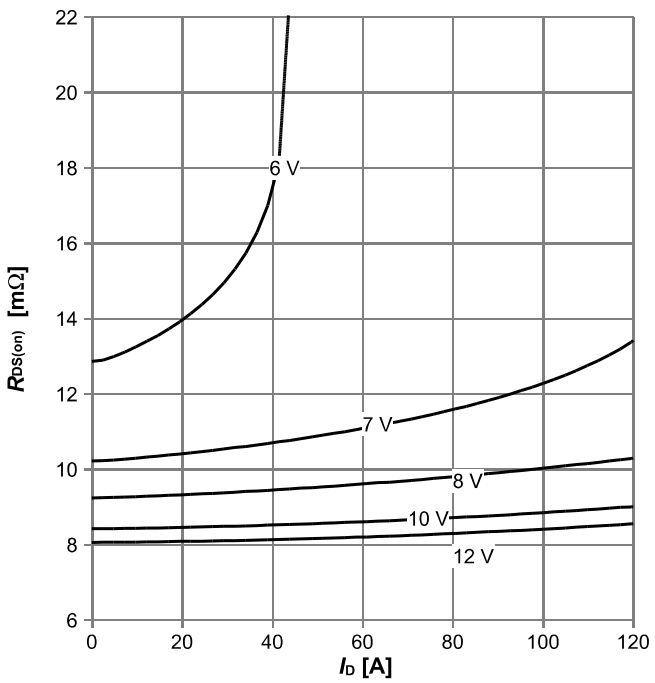
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 5: Typ. output characteristics



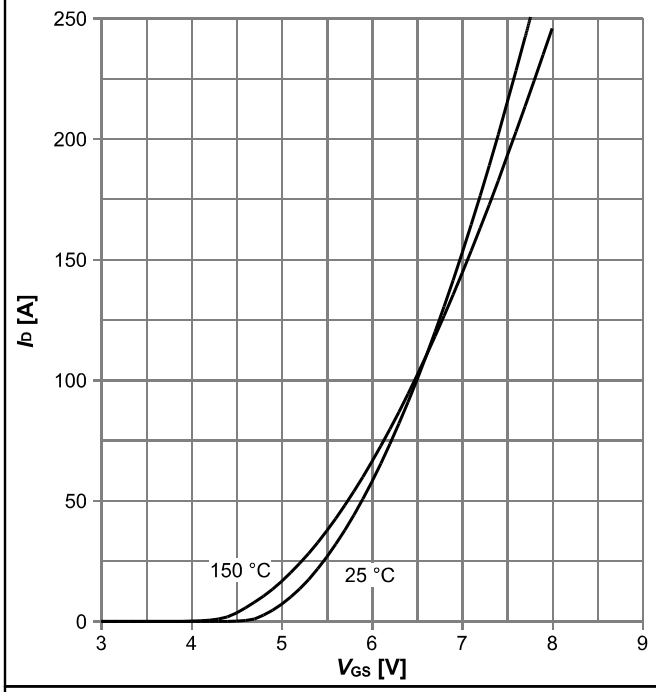
$I_D=f(V_{DS})$, $T_j=25$ °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



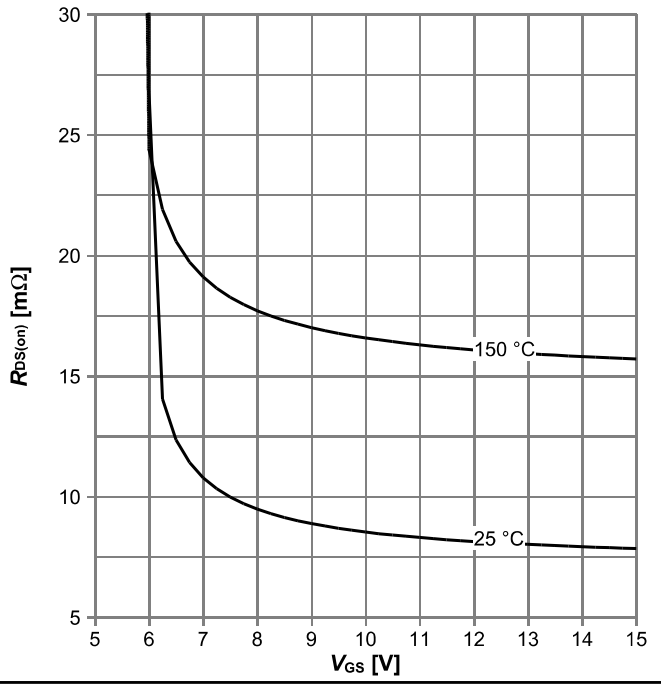
$R_{DS(on)}=f(I_D)$, $T_j=25$ °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



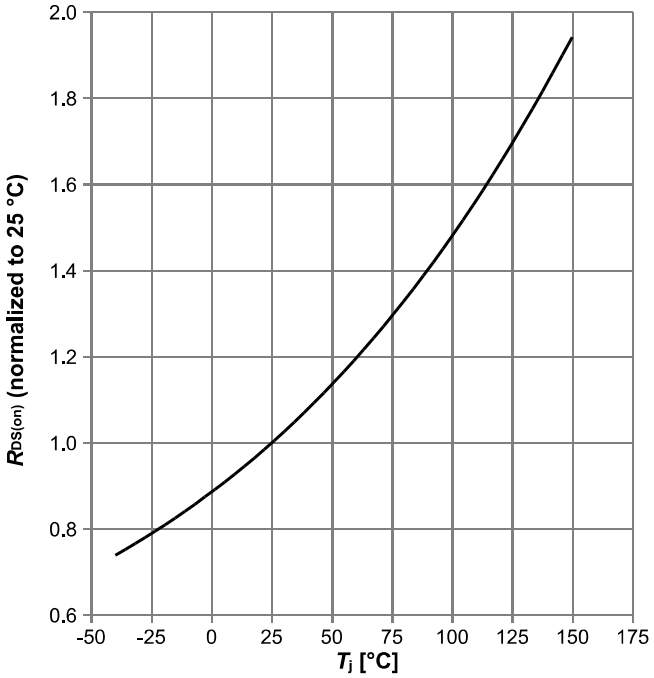
$I_D=f(V_{GS})$, $|V_{DS}|>2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



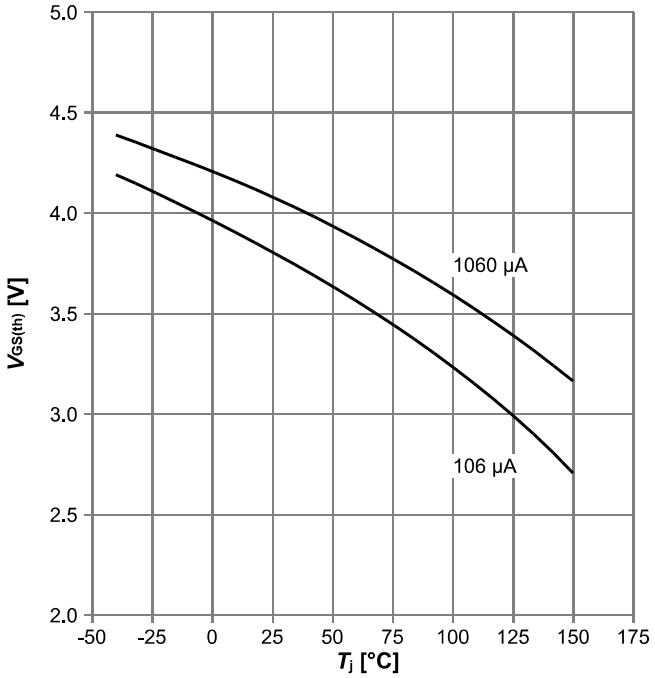
$R_{DS(on)}=f(V_{GS})$, $I_D=45$ A; parameter: T_j

Diagram 9: Normalized drain-source on resistance



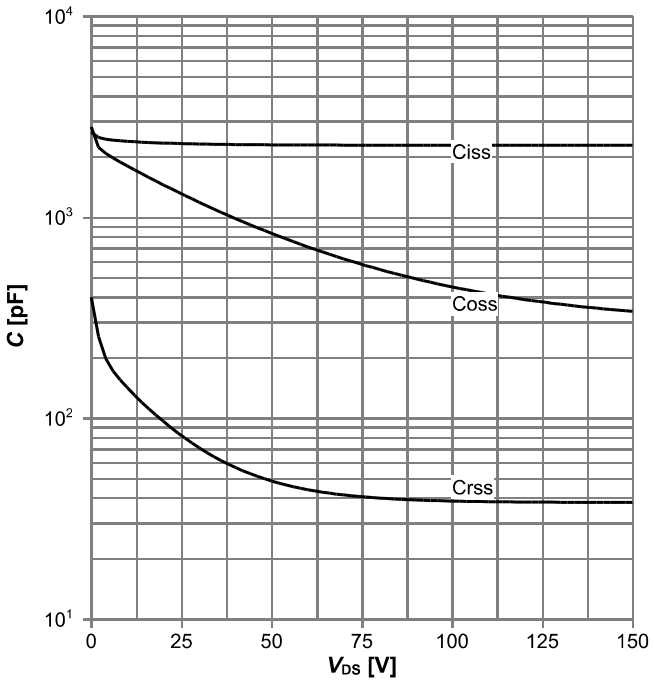
$R_{DS(on)}$=f(T_j), I_D=45 A, V_{GS}=10 V

Diagram 10: Typ. gate threshold voltage



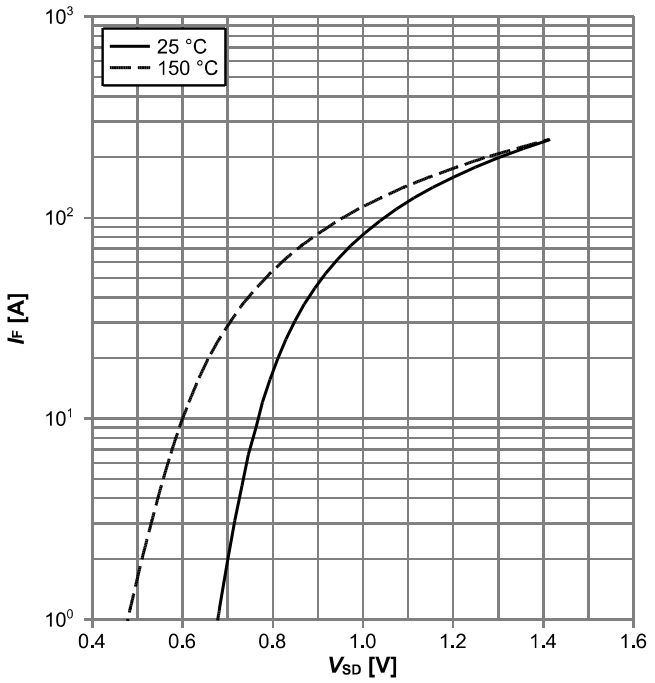
$V_{GS(th}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

Diagram 11: Typ. capacitances



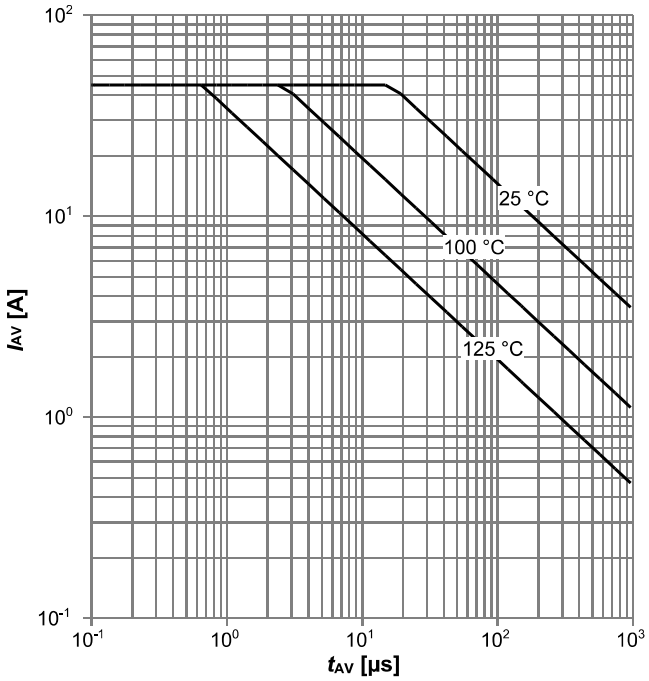
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 12: Typ. forward characteristics of reverse diode



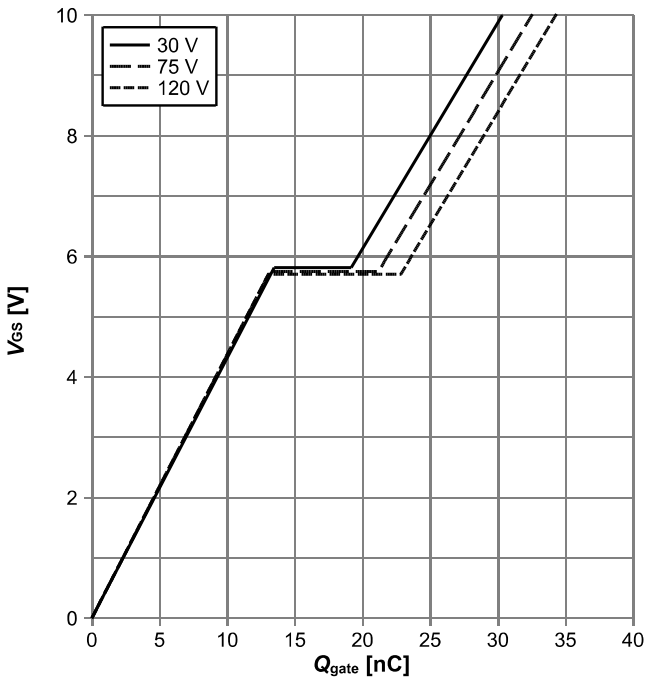
I_F=f(V_{SD}); parameter: T_j

Diagram 13: Avalanche characteristics



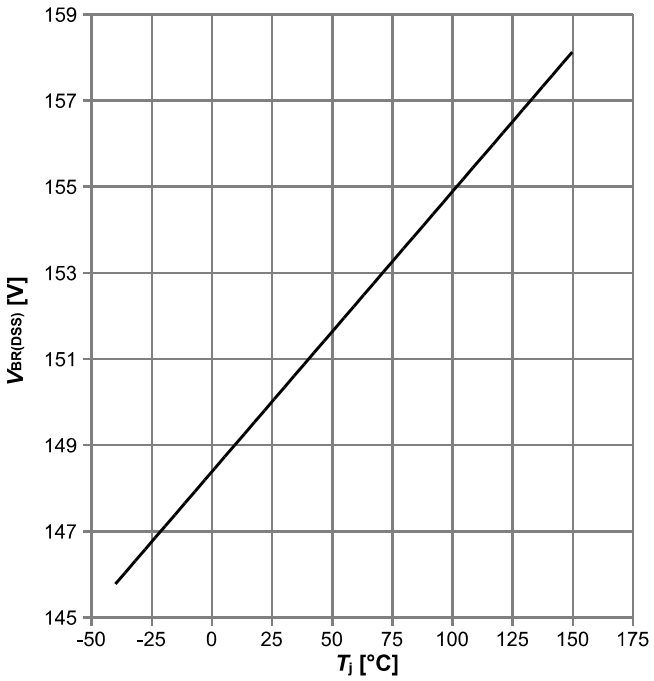
$I_{AS}=f(t_{AV})$; $R_{GS}=25\ \Omega$; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



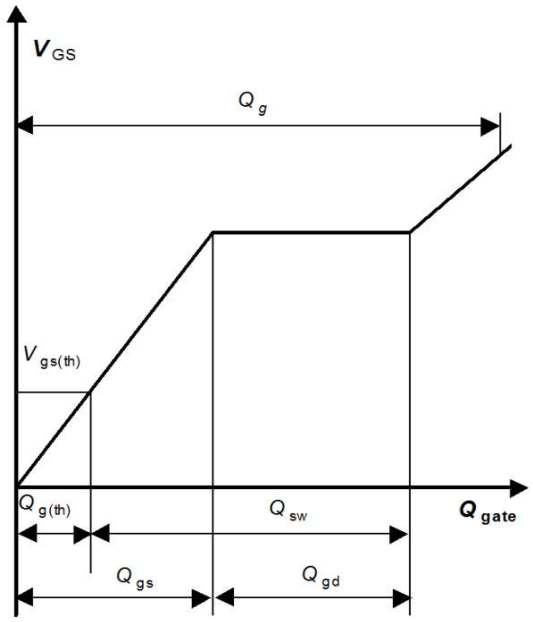
$V_{GS}=f(Q_{gate})$, $I_D=45$ A pulsed, $T_j=25$ °C; parameter: V_{DD}

Diagram 15: Min. drain-source breakdown voltage



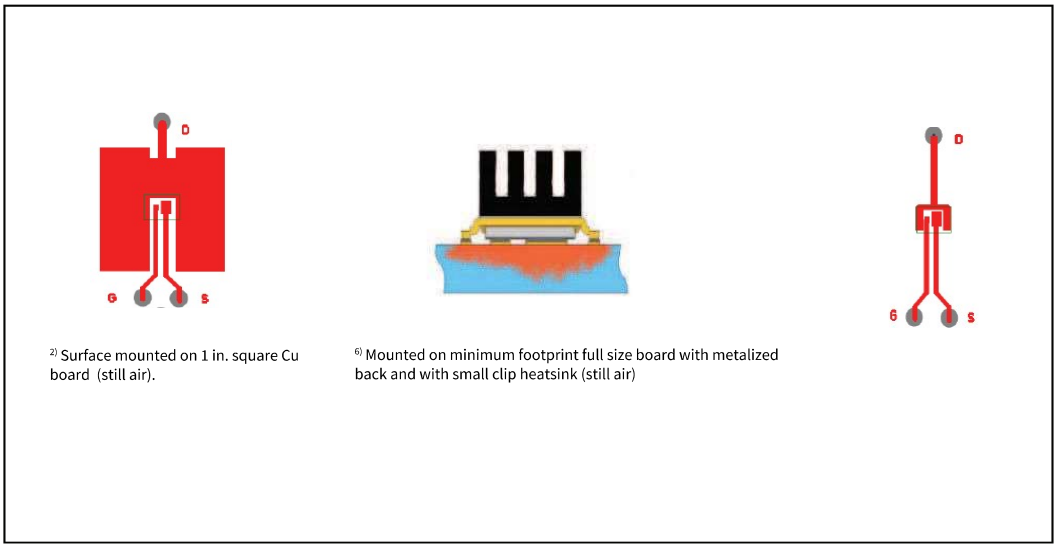
$V_{BR(DSS)}=f(T_j)$; $I_D=1$ mA

Diagram Gate charge waveforms



5 Test Circuits

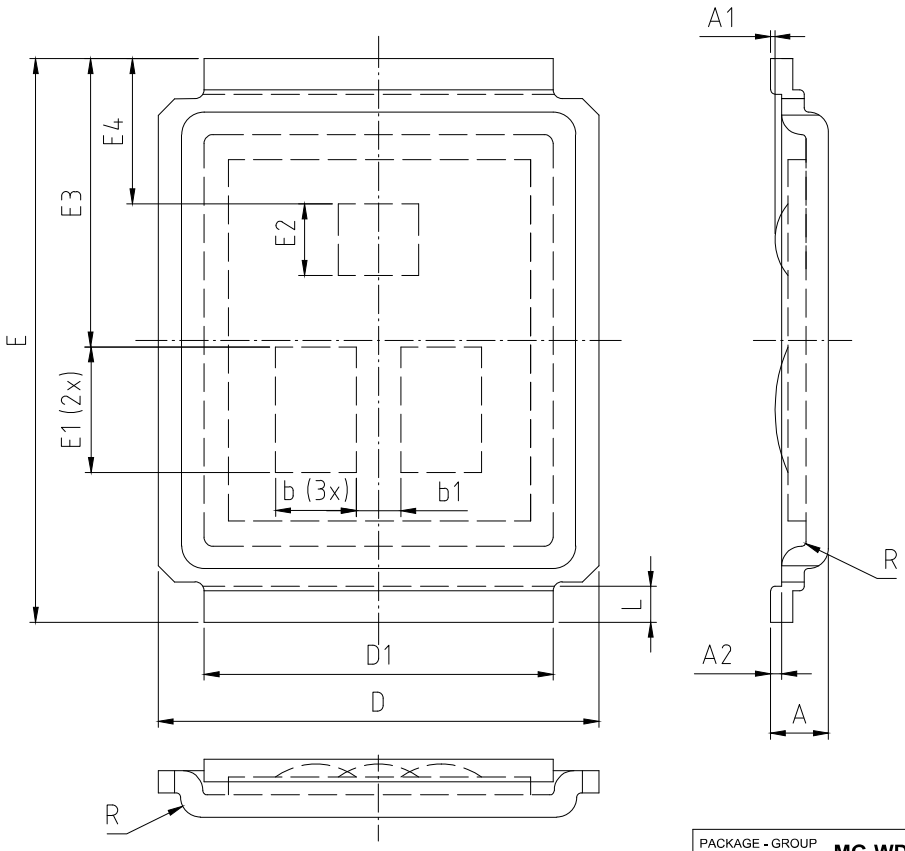
Table 8 Rth/Zth measurement diagrams



[2] Surface mounted on 1 in. square Cu board (still air).

[6] Mounted on minimum footprint full size board with metalized back and with small clip heatsink (still air)

6 Package Outlines



PACKAGE - GROUP NUMBER:	MG-WDSON-5-U02	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	0.59	0.70
A1	0.00	0.10
A2	0.08	0.17
b	0.88	0.92
b1	0.48	0.52
D	4.80	5.05
D1	3.85	3.95
E	6.25	6.35
E1	1.38	1.42
E2	0.78	0.82
E3	3.125	3.33
E4	1.525	1.73
L	0.35	0.45
R	---	0.10
N	5	

Figure 1 Outline MG-WDSON-5, dimensions in mm

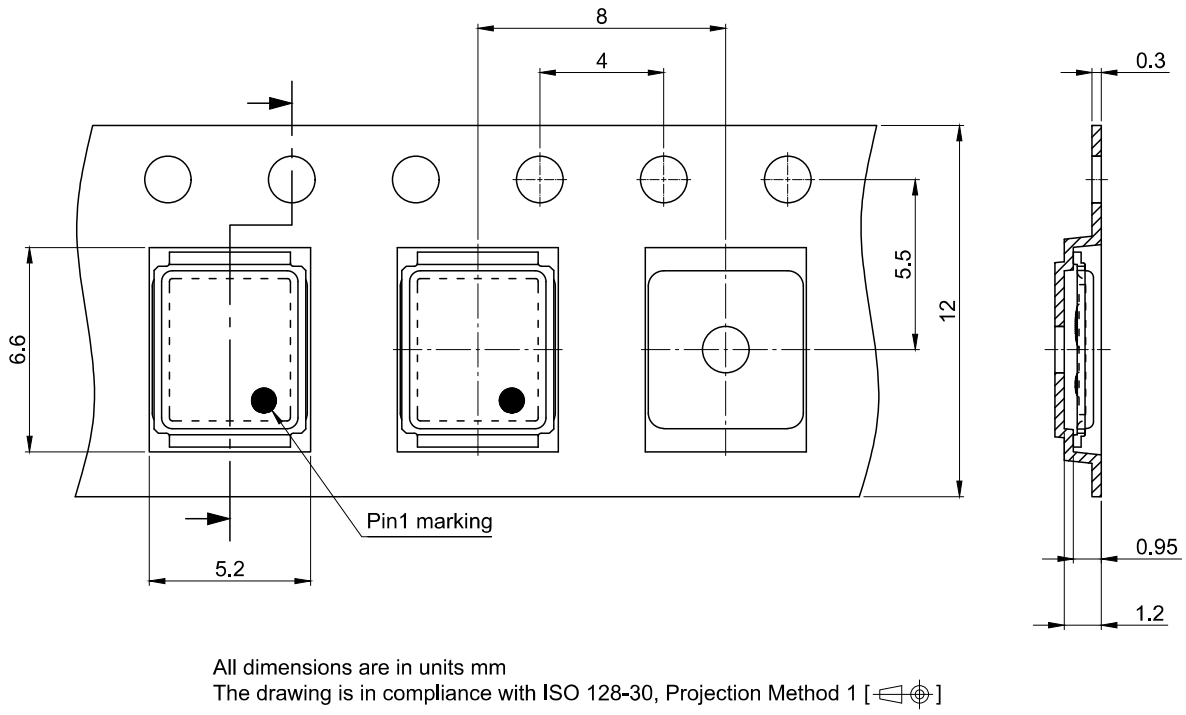


Figure 2 Outline Tape (MG-WDSON-5), dimensions in mm

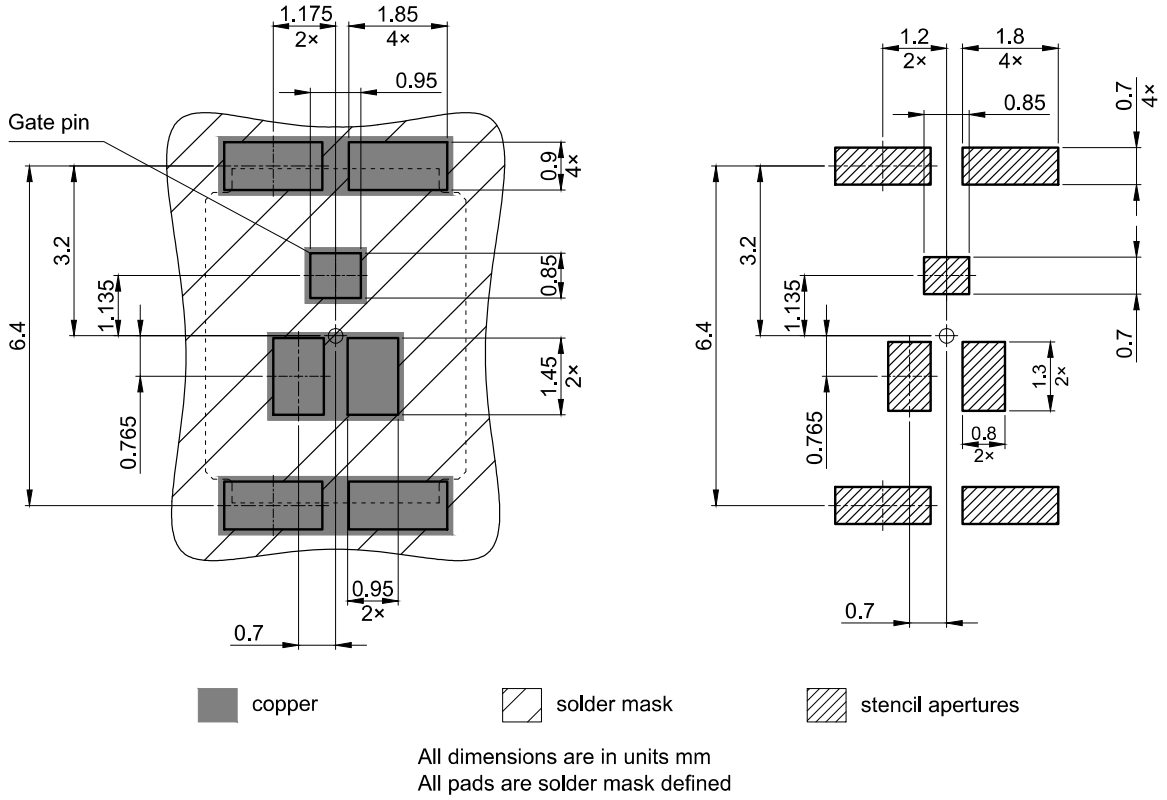


Figure 3 Outline Footprint (MG-WDSON-5), dimensions in mm

Revision History

IRF150DM115

Revision: 2023-08-29, Rev. 2.1

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2022-04-08	Release of final version
2.1	2023-08-29	Updated Rg, and outline_tape_footprint drawings

Trademarks
All referenced product or service names and trademarks are the property of their respective owners.

We Listen to Your Comments
Any information within this document that you feel is wrong, unclear or missing at all? Your feedback will help us to continuously improve the quality of this document. Please send your proposal (including a reference to this document) to:
erratum@infineon.com

Published by
Infineon Technologies AG
81726 München, Germany
© 2023 Infineon Technologies AG
All Rights Reserved.

Legal Disclaimer
The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics (“Beschaffenheitsgarantie”) .

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.
In addition, any information given in this document is subject to customer’s compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer’s products and any use of the product of Infineon Technologies in customer’s applications.
The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer’s technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

Information
For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings
Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.
The Infineon Technologies component described in this Data Sheet may be used in life-support devices or systems and/or automotive, aviation and aerospace applications or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support, automotive, aviation and aerospace device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.